

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE  
FOR REFLOW SOLDERINGAMENDMENTAssistant Commissioner for Patents  
Washington, D.C. 20231OFFICIAL  
FAX RECEIVED  
FEB 04 2002  
GROUP 1700

Dear Sir:

In response to the Official Action mailed on November 2, 2001, the period for responding to which extends through February 4, 2002, the Applicants request that the present application be amended as shown below.

IN THE CLAIMS:

Please rewrite the following claims as shown below. A marked-up version of the amended claims is found on Attachment A at the end of this amendment.

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\*\*\* ACTIVITY REPORT \*\*\*  
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RECEPTION OK

TX/RX NO.

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CONNECTION TEL

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START TIME

02/04 17:51

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RESULT

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